

Max. Marks : 100

Total Time : 3 Hours

PART A

(10 X 2 = 20 marks)

Answer **ALL** Questions

All questions carry equal marks

1. How are offset plates classified?
2. Explain what do you mean by "cylinder undercut"?
3. What do you mean by "Gripper Allowance"?
4. Why is a "Plate" used in an offset machine?
5. What is the purpose of plate clamp allowance in an offset machine ?
6. Define "Graining". in platemaking
7. What are the characteristics of a typical offset plate?
8. Why is grain direction important when planning images for platemaking.
9. When are wipe on plates used in an offset machine?
10. What are the advantages of using aluminium plates?

PART B

(5 X 16 = 80 marks)

Answer **ALL** Questions

All questions carry equal marks

11. Describe in detail with diagrams the automatic plate processing machine and its functioning.

12. (a) Explain in detail Electro photographic plates and waterless plates with diagrams

(OR)

(b) Describe in detail with appropriate diagrams the PS positive and Negative working plates.

13 (a) Explain in detail the various computer to plate systems used in offset platemaking.

(OR)

(b) Explain in detail with figures the various methods of image planning and layout preparation in offset platemaking.

14 (a) Describe the various light sources used in plate exposure and their advantages and disadvantages.

(OR)

(b) Explain in detail the factors involved in quality control and offset plate standardization

15 (a) Explain in detail the various plate handling methods and the safety precautions to be undertaken in the platemaking department.

(OR)

(b) Write short notes on

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| (i) | Diffusion transfer plates | (8) |
| (ii) | Platemaking software's and its features. | (8) |